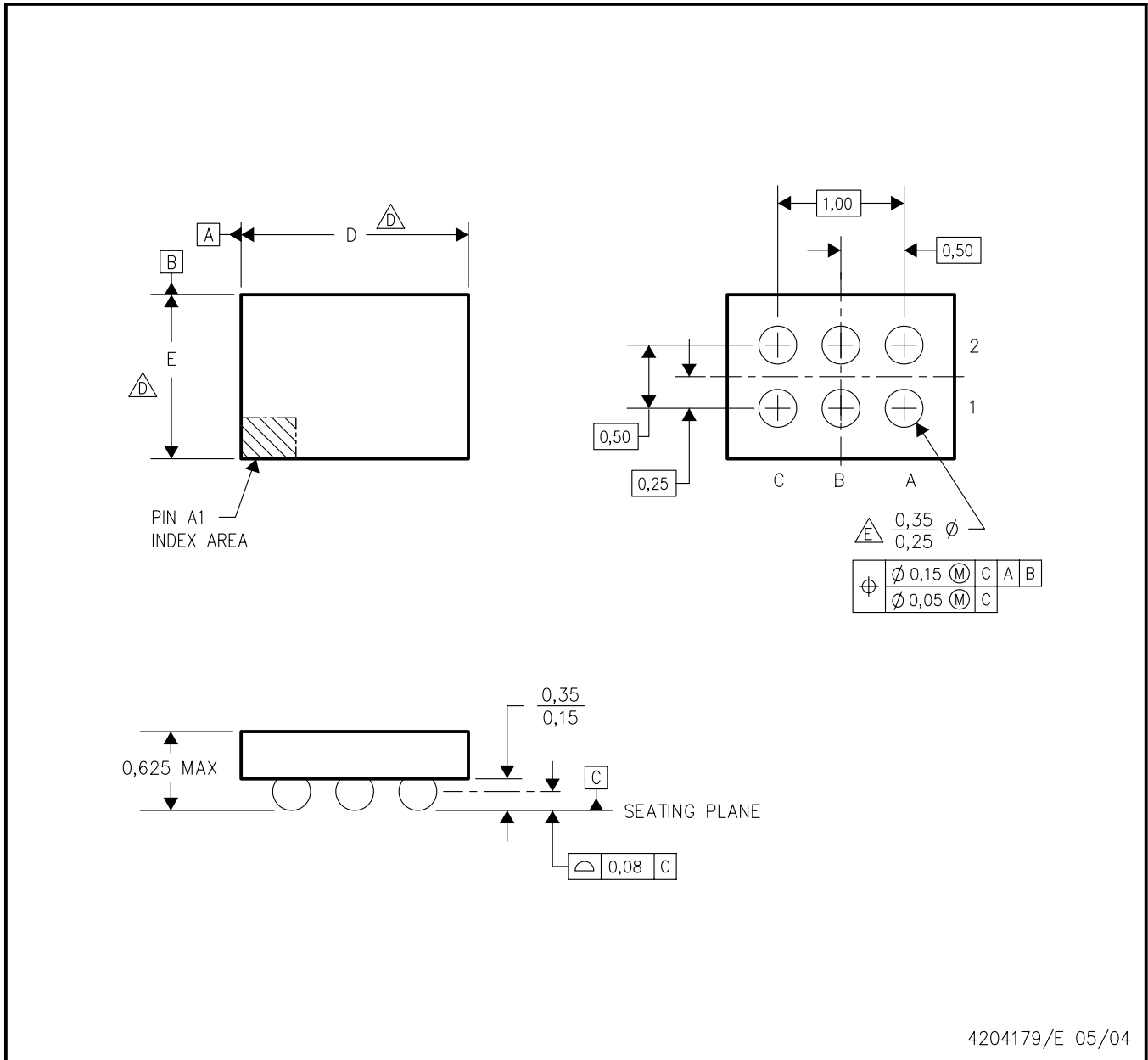


YEC (R-XBGA-N6)

DIE-SIZE BALL GRID ARRAY



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. NanoStar™ package configuration.
 - $\triangle D$ Devices in YEC package can have dimension D ranging from 1.35 to 2.15 mm and dimension E ranging from 0.85 to 1.65 mm. To determine the exact package size of a particular device, refer to the device datasheet or contact a local TI representative.
 - $\triangle E$ Reference Product Data Sheet for array population.
3 x 2 matrix pattern is shown for illustration only.
 - F. This package contains tin-lead (SnPb) balls.
Refer to YZC (Drawing #4205056) for lead-free balls.

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